

IN THE CLAIMS:

Please amend the claims as follows:

1. (Currently Amended) An automolding system comprising:
providing a substrate having a surface having a layer of resist on a portion thereof in the
automolding system;
a laser in the automolding system removing at least a portion of the layer of resist and at least a
portion of the contaminants from the substrate using a laser in the automolding system; and
scanning the substrate using a laser in the automolding system for irregularities from removing
the layer of resist; and
a cooling system for the laser.

2. (Previously Presented) The automolding system of claim 1, wherein the laser
comprises one of an Nd:YAG laser and an excimer laser.

3. (Previously Presented) The automolding system of claim 1, further comprising:
a mold; and
encapsulating the substrate in the mold in the automolding system.

4. (Currently Amended) A molding system comprising:
providing a substrate having a surface having a layer of resist on a portion thereof in the molding
system;
a laser in the molding system removing at least a portion of the layer of resist and contaminants
from the substrate using a laser in the the molding system; and scanning the substrate using a
laser in the automolding system for irregularities from removing the layer of resist; and
a cooling system for the laser.

5. (Previously Presented) The molding system of claim 4, wherein the laser
comprises one of an Nd:YAG laser and an excimer laser.

6. (Previously Presented) The molding system of claim 4, further comprising:
a mold in the molding system for encapsulating the substrate.

7. (Currently Amended) A system for molding comprising:
providing a substrate having a surface having a layer of resist on a portion thereof for molding in
the system;
a laser in the molding system cutting a portion of the layer of resist using a laser in the molding
system; and removing at least a portion of the layer of resist and some contaminants from the
substrate using a laser in molding system; and
a cooling system for the laser.

8. (Previously Presented) The system of claim 7, wherein the laser comprises one of
an Nd:YAG laser and an excimer laser.

9. (Previously Presented) The system of claim 7, further comprising:
a mold in the system for encapsulating the substrate.

10. (Currently Amended) An automolding system comprising:
placing a substrate having a surface having a layer of resist on a portion thereof placed in the
automolding system;
a laser in the automolding system cutting a portion of the layer of resist using a laser in the
molding system; and removing at least a portion of the layer of resist and at least some of the
contaminants from the substrate using a laser in the automolding system; and
a cooling system for the laser in the molding system.

11. (Previously Presented) The automolding system of claim 10, wherein the laser
comprises one of an Nd:YAG laser and an excimer laser.

12. (Previously Presented) The automolding system of claim 10, further comprising:
a mold for encapsulating the substrate in the automolding system.

13. (Currently Amended) In a molding system comprising:
placing a substrate having a semiconductor device thereon, the substrate having a surface having
a layer of resist on at least a portion thereof in the molding system;
a laser in the molding system removing at least a portion of the layer of resist and at least some of
the contaminants from the substrate using a laser in the molding system; and marking a surface of
the semiconductor die using the laser in the molding system; and
a cooling system for the laser in the molding system.

14. (Previously Presented) In the molding system of claim 13, wherein the laser
comprises one of an Nd:YAG laser and an excimer laser.

15. (Previously Presented) In the molding system of claim 13, further comprising:
a mold in the molding system for encapsulating the substrate.

16. (Currently Amended) A system for molding comprising:
placing a substrate having a semiconductor device thereon, the substrate having a surface having
a layer of resist on at least a portion thereof for molding in the system;
a laser in the system for molding having more than one transmission unit removing at least a
portion of the layer of resist and at least some of the contaminants from the substrate using a
laser in the automolding system; and marking a surface of the semiconductor device using the
laser in the automolding system; and
a cooling system for the laser in the molding system.

17. (Previously Presented) The system of claim 16, wherein the laser comprises one
of an Nd:YAG laser and an excimer laser.

18. (Previously Presented) The system of claim 16, further comprising:
a mold in the system for encapsulating the substrate.

19. (Currently Amended) An automolding system having a cleaning apparatus comprising:
introducing a substrate having a semiconductor device thereon, the substrate having a surface having a portion thereof covered with a layer of resist in the automolding system;
a laser in the automolding system having more than one transmission unit cutting a portion of the layer of resist; removing at least a portion of the layer of resist and at least some of the contaminants from the substrate using a laser in the automolding system; and marking a surface of the semiconductor device using the laser in the automolding system; and
a cooling system for the laser in the automolding system.

20. (Previously Presented) The automolding system of claim 19, wherein the laser comprises one of an Nd:YAG laser and an excimer laser.

21. (Previously Presented) The automolding system of claim 19, further comprising:
a mold for encapsulating the substrate in the automolding system.

22. through 40. (Canceled)